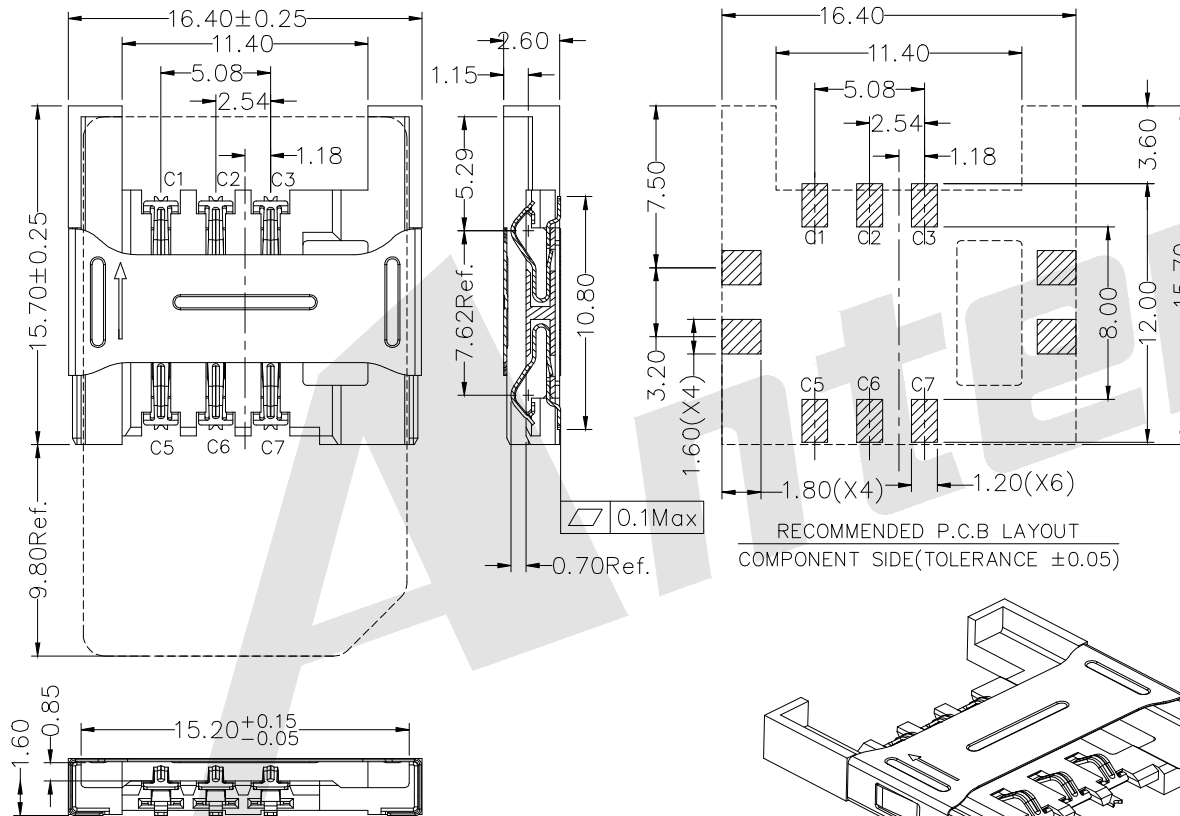


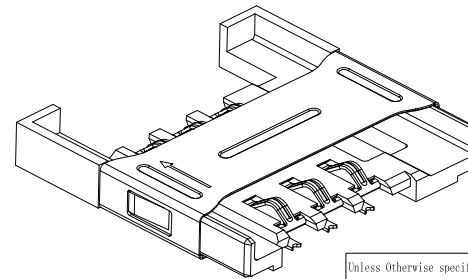
HSF



TECHNICAL CHARACTERISTICS
 1.General Characteristics
 Dimension:15.70L*16.40W*2.60H MM
 Weight:Approx0.52±0.2g
 Durability:5000 Cycles Min
 2.Electical Characteristics
 Contact Resistance: 50mΩ Typical,100mΩ max
 Insulation Resistance:>1000MΩ/500V DC
 3.Solderability
 Vaporphase:215° C,30Sec.Max
 Ir Reflow:250° C,5Sec.Max
 Manual Soldering:370° C,3Sec.Max
 4.Environmental Characteristics
 Operating Temperature:-40° C+85° C
 Operating Humidity:10%+95%RH



PART NUMBER:
 ATK - SIM 6 260 A C742
 SERIES NUMBER
 Packing
 A:Tray
 T:Tube
 R:Tape&Reel
 260=2.60mm
 6=6Pin
 ATK- COMPANY NAME



Unless Otherwise specified tolerance
 X. ±0.35 X.XX: ±0.20
 X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown UNIT: mm

DRAW Wu Feng Rong DATE 25/03/2020

CHECK BobYang DATE 25/03/2020



3rd ANGLE PROJECTION

Antenk® ANTENK ELECTRONICS CO.,LTD
 Http://www.antenk.com
 E-mail:sales@antenk.com

TITLE: SIM Card 6Pin Shorter Tall
 2.60mm Height Connector

DRAWING NO: ATK-SIM6260AC742

PRODUCT NO: ATK-SIM6260AC742

REV		DESCRIPTION		DATE			
1	2	3	4	5	6	7	8